PCB Pad Definition and Traces

The HMC5883L is a fine pitch LCC package. Refer to previous figure for recommended PCB footprint for proper package centering. Size the traces between the HMC5883L and the external capacitors (C1 and C2) to handle the 1 ampere peak current pulses with low voltage drop on the traces.

Stencil Design and Solder Paste

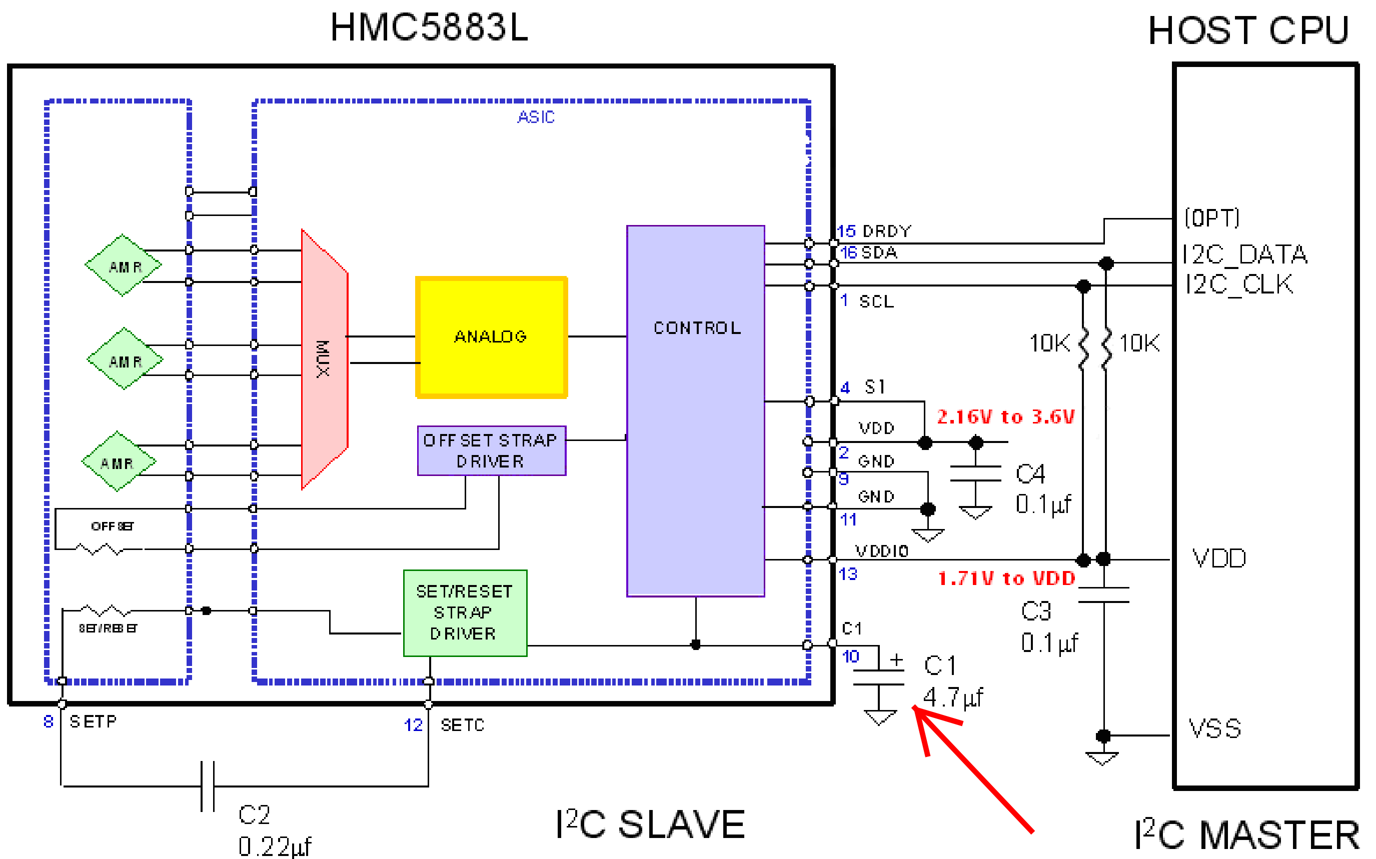
A 4 mil stencil and 100% paste coverage is recommended for the electrical contact pads.

Reflow Assembly

This device is classified as MSL 3 with 260°C peak reflow temperature. A baking process (125°C, 24 hrs) is required if device is not kept continuously in a dry (< 10% RH) environment before assembly. No special reflow profile is required for HMC5883L, which is compatible with lead eutectic and lead-free solder paste reflow profiles. Honeywell recommends adherence to solder paste manufacturer's guidelines.

INTERNAL SCHEMATIC DIAGRAM

HMC5883L



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